

LN1471YTR

Surface Mounting Chip LED

S-GW Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|-------------------------------|-----------|-------------|------------------|
| Power dissipation | P_D | 60 | mW |
| Forward current | I_F | 20 | mA |
| Pulse forward current * | I_{FP} | 60 | mA |
| Reverse voltage | V_R | 4 | V |
| Operating ambient temperature | T_{opr} | -25 to +85 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -30 to +100 | $^\circ\text{C}$ |

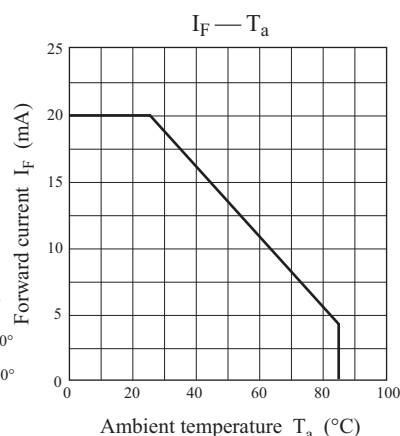
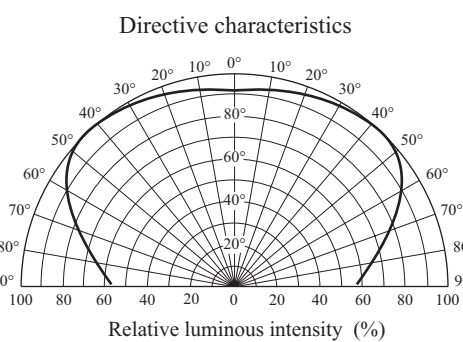
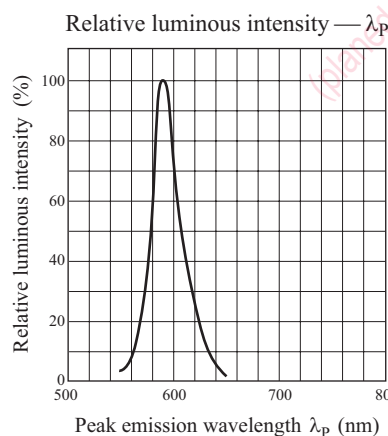
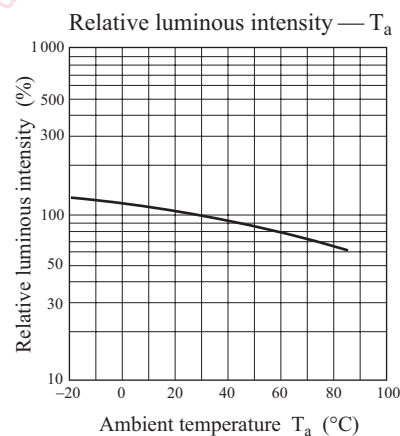
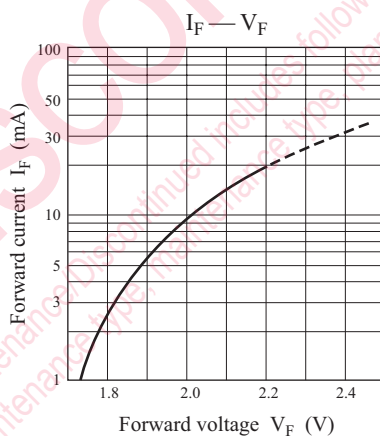
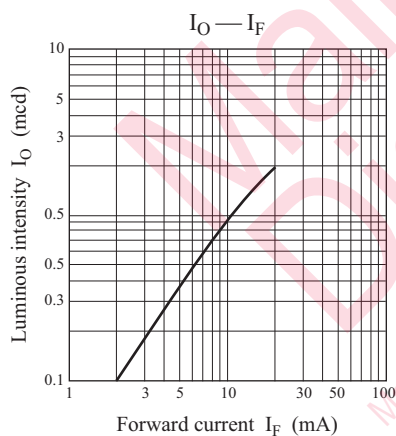
■ Lighting Color

- Amber

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

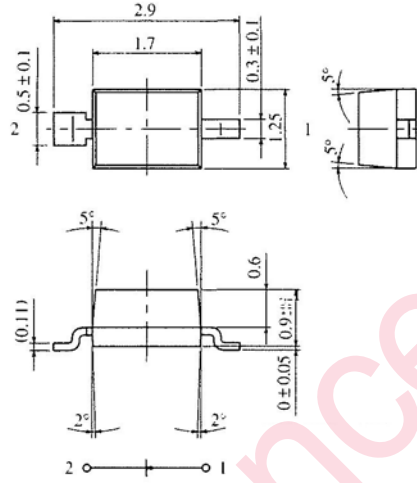
■ Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--------------------------|-----------------|----------------------|-----|-----|-----|---------------|
| Luminous intensity | I_O | $I_F = 10\text{ mA}$ | 0.4 | 1.0 | | mcd |
| Reverse current | I_R | $V_R = 4\text{ V}$ | | | 10 | μA |
| Forward voltage | V_F | $I_F = 10\text{ mA}$ | | 2.0 | 2.6 | V |
| Peak emission wavelength | λ_p | $I_F = 10\text{ mA}$ | | 590 | | nm |
| Spectral half band width | $\Delta\lambda$ | $I_F = 10\text{ mA}$ | | 30 | | nm |



■ Package (Unit: mm)

LLTFTN2G0600



- Pin name
- 1: Anode
- 2: Cathode

Maintenance/Discontinued

Maintenance/Discontinued includes following four Product lifecycle stage.
(planned maintenance type, maintenance type, planned discontinued type, discontinued type)

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